

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A computing system comprising:
  - a circuit board;
  - a first device having a first heat transfer surface;
  - a first heat sink including:
    - a first base thermally coupled to the first heat transfer surface; and
    - a first array of fins thermally coupled to the first base so as to extend away from the first base in a first direction, wherein the first array of fins includes consecutive fins forming a transverse channel therebetween extending in a second direction perpendicular to the first direction and having opposite transverse open ends;
  - a second device coupled to the circuit board, the second device having a second heat transfer surface; and
  - a second heat sink including:
    - a second base thermally coupled to the second heat transfer surface;and
  - a second array of fins coupled to the second base and extending at least partially across the first array of fins.
2. (Original) The system of Claim 1, wherein the first device is electrically connected to the second device.
3. (Currently Amended) The system of Claim 1, wherein the first array of fins overlaps the first device and wherein the first device generates heat at a first rate and wherein the second device generates heat at a second greater rate.
4. (Currently Amended) The system of Claim 1, wherein the second device comprises a processor assembly including a central processing unit and wherein the second base is configured to conduct heat from the central processing unit to the second array of fins without conducting heat to the first base.

5. (Original) The system of Claim 4, wherein the first device comprises a power pod assembly.
6. (Original) The system of Claim 5, wherein the power pod assembly is dedicated solely to supplying power to the processor assembly.
7. (Currently Amended) The system of Claim 1, wherein the first array of fins extends over the first base which overlaps the first device and wherein the first device comprises a power pod assembly.
8. (Currently Amended) The system of Claim 1, wherein the second array of fins overlaps ~~extends on~~ opposite sides of the first device.
9. (Original) The system of Claim 1, wherein the second heat sink includes a heat pipe extending at least partially across the first array of fins.
10. (Original) The system of Claim 9, wherein the heat pipe supports the second array of fins over the first array of fins.
11. (Original) The system of Claim 9, wherein the heat pipe extends at least partially along the second base.
12. (Original) The system of Claim 9, wherein the heat pipe extends from below the first base to above the first array of fins.
13. (Original) The system of Claim 1, wherein the first device and the second device are coupled to one another to form a multi-device module adapted to be connected to the circuit board.
14. (Original) The system of Claim 1 including:
  - a third device having a third heat transfer surface;
  - the third heat sink including:
    - a third base thermally coupled to the third heat sink; and
    - a third array of fins thermally coupled to the third base;
  - a fourth device coupled to the circuit board, the fourth device having a fourth heat transfer surface; and

a fourth heat sink including:

a fourth base thermally coupled to the fourth heat transfer surface; and

a fourth array of fins coupled to the fourth base and extending at least partially across the third array of fins.

15. (Original) The system of Claim 14 including a central electronic control coupled to the circuit board.

16. (Original) The system of Claim 14 including:

a baseboard coupled to the circuit board;

a memory device coupled to the baseboard; and

an input/output device coupled to the baseboard.

17. (Original) The system of Claim 14 including a fan configured to create an air flow across the second device and across the fourth device.

18. (Original) The system of Claim 1, wherein at least one of the first array of fins is interleaved with the second array of fins.

19. (Currently Amended) A multi-device heat sink module adapted to be connected to a circuit board, the module comprising:

a first device having a first heat transfer surface;

a first heat sink having a first base thermally coupled to the first heat transfer surface, wherein the first heat sink includes a first array of fins thermally coupled to the first base;

a second device coupled to the first device and having a second heat transfer surface;

a second heat sink having a second base thermally coupled to the second heat transfer surface, wherein the second heat sink includes a second array of fins, wherein the second array of fins extends at least partially across the first array of fins, wherein the second heat sink includes a heat pipe extending at least partially across the first array of fins from below the first base to above the first array of fins; and

a connector connected to one of the first device and the second device and configured to be electrically connected to the circuit board, wherein at least a portion of the second heat sink extends at least partially across the first heat sink.

20. (Canceled)
21. (Canceled)
22. (Canceled)
23. (Currently Amended) The module of Claim 19 ~~22~~, wherein the second array of fins overlaps ~~extends on~~ opposite sides of the first array of fins.
24. (Canceled)
25. (Currently Amended) The module of Claim 19 ~~24~~, wherein the heat pipe extends at least partially along the second base.
26. (Canceled)
27. (Original) The module of Claim 19, wherein the first device is electrically connected to the second device.
28. (Original) The module of Claim 19, wherein the first device generates heat at a first rate and wherein the second device generates heat at a second greater rate.
29. (Original) The module of Claim 19, wherein the second device comprises a processor assembly including a central processing unit.
30. (Original) The module of Claim 29, wherein the first device comprises a power pod assembly.
31. (Original) The module of Claim 30, wherein the power pod assembly is dedicated solely to supplying power to the processor assembly.
32. (Original) The module of Claim 19, wherein the first device comprises a power pod assembly.
33. (Original) The module of Claim 18, wherein the second heat sink includes:  
a heat pipe extending above the first heat sink; and  
an array of fins thermally coupled to the heat pipe and supported by the heat pipe above the first heat sink.

34. (Currently Amended) A processor module comprising:  
a processor configured to be connected to a circuit board, the processor having a first heat transfer surface;  
a power pod electrically connected to the processor to supply power to the processor, the power pod having a second heat transfer surface;  
a first heat sink overlapping the power pod and thermally coupled to the second heat transfer surface; and  
a second heat sink thermally coupled to the first heat transfer surface, wherein the second heat sink extends at least partially across the first heat sink.

35. (Original) The module of Claim 34, wherein the second heat sink extends completely across the first heat sink.

36. (Original) The module of Claim 35, wherein the second heat sink extends on opposite sides of the first heat sink.

37. (Currently Amended) A multi-device heat sink module for being connected to a circuit board, the module comprising:  
a power supply first device emitting heat;  
a processor second device emitting heat;  
a first means for dissipating heat emitted by the first device power supply while not substantially receiving heat from the processor; and  
a second means for dissipating heat emitted by the processor second device, wherein the second means extends at least partially across the first means.

38. (Canceled)

39. (Currently Amended) A heat dissipating arrangement comprising:  
a first heat emitting device;  
a second heat emitting device; and  
a first heat sink having fins thermally coupled to the first device, wherein the fins of the first heat sink extends on overlap opposite sides of the second device.

40. (Original) The arrangement of Claim 39 including a second heat sink thermally coupled to the second device, wherein the first heat sink extends on opposite sides of the second heat sink.

41. (Currently Amended) A first heat sink for use with a first heat emitting device, a second heat emitting device and a second heat sink thermally coupled to the second heat emitting device, the first heat sink comprising:

at least one heat dissipating structure having fins configured to be thermally coupled to the first heat emitting device while extending at least partially around and on opposite sides of the second heat sink.

42. (Currently Amended) A first heat sink for use with a first heat emitting device, a second heat emitting device, and a second heat sink thermally coupled to the second heat emitting device and having a plurality of fins, the first heat sink comprising:

at least one heat dissipating structure configured to be thermally coupled to the first heat emitting device while extending at least partially across around and on opposite sides of the plurality of fins of the second heat sink.

43. (Currently Amended) A method for dissipating heat from a first electronic device positioned proximate a second electronic device, the method comprising:

directing heat generated by the first device through a first array of fins extending across and around at least a portion of the second device so as to dissipate heat on opposite sides of the portion of the second device.

44. ((Currently Amended) The method of Claim 43, wherein the second device includes a first second array of fins ~~heat dissipating surfaces~~ and wherein the method further includes nesting the first second array of fins ~~device~~ within the first array of fins ~~heat dissipating surfaces~~.

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45. (Canceled)

46. (New) The system of claim 1, wherein the first base is horizontally spaced from and beside the second base.

47. (New) A computing system comprising:

a circuit board;

a first device having a first heat transfer surface;

a first heat sink including:

a first base thermally coupled to the first heat transfer surface; and

a first array of fins thermally coupled to the first base;

a second device coupled to the circuit board, the second device having a second heat transfer surface; and

a second heat sink including:

a second base thermally coupled to the second heat transfer surface; and

a second array of fins coupled to the second base and extending at least partially across the first array of fins, wherein at least one of the first array of fins is interleaved with the second array of fins.